

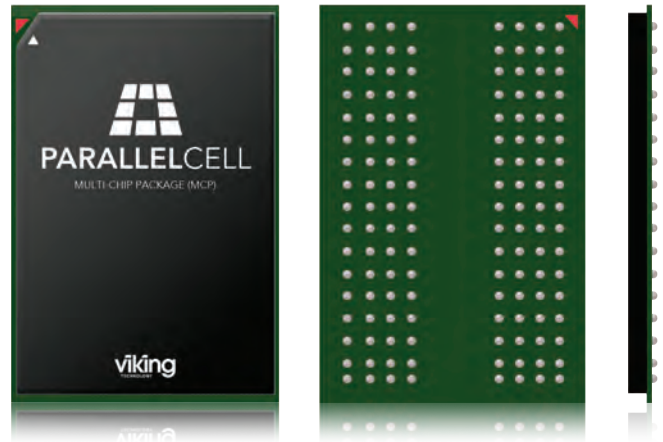
PRODUCT BRIEF | MCP

PARALLELCCELL

MULTI-CHIP PACKAGE (MCP)

Ultra High Density Memory Solution for Embedded Applications

Viking Technology ParallelCell Multi-Chip Package (MCP) is part of the extreme density line of DDR3 and DDR4 memory products optimized for the embedded, industrial, and military/aerospace markets. ParallelCell products achieve significantly higher memory performance and density per cubic inch than conventional memory DIMMs. These performance and density milestones will critically change the way future system hardware is designed and deployed.

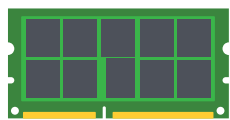


BENEFITS

Very small footprint: Saves up to 85% board space vs. Standard DIMM Modules	Very high memory capacity per cu. in.	Very high memory bandwidth per cu. in.
Rugged: Soldered-down PBGA – No DIMM connector	Superior signal integrity	Lower cost motherboard due to easier DDR routing



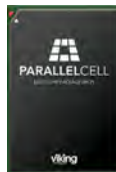
4GB LRDIMM (133.35mm x 30mm)



4GB SODIMM (67.6mm x 30mm)



4GB MINI-DIMM (82mm x 30mm)



Actual size

4GB PARALLELCCELL MCP
(15mm x 20mm)

A full size module in a ultra small form factor MCP.

- Up to 85% Space savings
- Ruggedization
- Optimized for embedded applications
- Greater I/O per cu. in.

PARALLELCELL MULTI-CHIP PACKAGE (MCP)

Ultra High Density Memory Solution for Embedded Applications

SPEEDS		VOLTAGE	
DDR3	1333/1600/1866	DDR3	1.5V/1.35V
DDR4	2133/2400/2667	DDR4	1.2V

TEMPERATURE	
Industrial	-40°C to 85°C
Extended	-40°C to 105°C
Military	-55°C to 125°C

DDR3 / DDR4 MULTI-CHIP PACKAGE

VIKING P/N	DDR TYPE	# MEMORY WORDS (M)	BUS WIDTH*	# CHANNELS	MODULE DENSITY	PACKAGE SIZE (MM)	PACKAGE HEIGHT	BALL COUNT	BALL PITCH
VPM7U1240D6B3PD1xyz	DDR3	512	40	2 (BANK A & BANK B)	4GB	15 x 20	1.9mm	321	0.8mm
VPM7U1240D6B3PF1xyz	DDR3	512	40	2 (BANK A & BANK B)	4GB	15 x 20	1.9mm	321	0.8mm
VPM7U1240D6B3PG1xyz	DDR3	512	40	2 (BANK A & BANK B)	4GB	15 x 20	1.9mm	321	0.8mm
VPM7U1272S6B3PD1xyz	DDR3	512	72	1	4GB	15 x 20	1.9mm	321	0.8mm
VPM7U1272S6B3PF1xyz	DDR3	512	72	1	4GB	15 x 20	1.9mm	321	0.8mm
VPM7U1272S6B3PG1xyz	DDR3	512	72	1	4GB	15 x 20	1.9mm	321	0.8mm
VPM9U1232D6B0PG1xyz	DDR4	512	32	2	4GB	15 x 20	1.9mm	391	0.8mm
VPM9U1232D6B0PH1xyz	DDR4	512	32	2	4GB	15 x 20	1.9mm	391	0.8mm
VPM9U1232D6B0PJ1xyz	DDR4	512	32	2	4GB	15 x 20	1.9mm	391	0.8mm
VPM9U1232D6B0PK1xyz	DDR4	512	32	2	4GB	15 x 20	1.9mm	391	0.8mm
VPM9U1240D6B0PG1xyz	DDR4	512	40	2	4GB	15 x 20	1.9mm	391	0.8mm
VPM9U1240D6B0PH1xyz	DDR4	512	40	2	4GB	15 x 20	1.9mm	391	0.8mm
VPM9U1240D6B0PJ1xyz	DDR4	512	40	2	4GB	15 x 20	1.9mm	391	0.8mm
VPM9U1240D6B0PK1xyz	DDR4	512	40	2	4GB	15 x 20	1.9mm	391	0.8mm
VPM9U1272S6B0PG1xyz	DDR4	512	72	1	4GB	15 x 20	1.9mm	391	0.8mm
VPM9U1272S6B0PH1xyz	DDR4	512	72	1	4GB	15 x 20	1.9mm	391	0.8mm
VPM9U1272S6B0PJ1xyz	DDR4	512	72	1	4GB	15 x 20	1.9mm	391	0.8mm
VPM9U1272S6B0PK1xyz	DDR4	512	72	1	4GB	15 x 20	1.9mm	391	0.8mm

* Dual channel devices may be configured to a signal channel with 2X word width by connecting both sets of address/command/control pins.

For price and availability, please email us at sales@vikingtechnology.com.



Global Locations

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For all of our global locations, visit our website under global locations. For sales information, email us at sales@vikingtechnology.com